

Supply Chain Explorer

By the Emerging Technology Observatory

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Substrates

Protective ceramic packages, plastic substrates, or encapsulant resins may be bonded to a chip during the packaging process.

Country provision

- China (mainland)
- Japan
- South Korea
- Taiwan

Notable supplier companies

- AKM - China (mainland)
- Ibiden - Japan
- NanYa - Taiwan
- Samsung - South Korea
- Shennan Circuits - China (mainland)
- Shinko - Japan
- Zhuhai Yueya - China (mainland)